



IAP08Rec'd PCT 26 NOV 2008

**PATENT APPLICATION**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Isao YOKOKAWA

Group Art Unit: 2812

Application No.: 10/584,771

Examiner: C. LEE

Filed: June 28, 2006

Docket No.: 128503

For: METHOD FOR MEASURING AN AMOUNT OF STRAIN OF A BONDED  
STRAINED WAFER

**AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the November 14, 2008, Office Action issued under Ex parte Quayle,  
please consider the following:

**Amendments to the Specification;**

**Amendments to the Claims** as reflected in the listing of claims; and

**Remarks.**